

Raytheon Quality Note
CX

Revision - Date
2 – 11/15/07

Soldering Requirements (IPC J-STD-001D)

IPC J-STD-001D, Class 3 (Requirements for Soldering Electrical and Electronic Assemblies) with the modifications listed below is a requirement of this purchase order.

Note: This Quality Note is NOT intended to apply to Component Parts or Component Assemblies subject to soldering at a higher level of assembly where reflow could take place. It is understood that High Temperature Solders are appropriate and required to prevent solder reflow at a higher level of assembly.

- a. Solder alloys, such as Sn60Pb40, Sn62Pb36Ag2, and Sn63Pb37, shall be in accordance with J-STD-006. Other solder alloys **shall not** be used for electrical and electronic assembly soldering unless otherwise specified on the drawing or purchase order. (Reference J-STD-001D Para. 3.2)
- b. Process Validation and control cannot be substituted for 100% X-Ray inspection of Ball Grid Arrays (BGAs) unless it is part of a documented process control program agreed to by the Raytheon procuring agency. (Reference J-STD-001 Para. 7.6.14).
- c. Supplier will comply with J-STD-001D Paragraph 9.1.10 Measling, unless the Printed Circuit Board (PCB) is procured to a specification in which a greater level of measling is acceptable, such as IPC-6012 and IPC-6013, then the assemblies will use the criteria called out therein. Measling should be identified as a Process Indicator as defined in J-STD-001D Paragraph 1.5.1.

Compliance to the requirements of this standard is subject to Raytheon review at any time during the performance of this order.

This document is an integral part of the contract (purchase order), which calls it out. The revision in effect at the time the purchase order was placed applies.